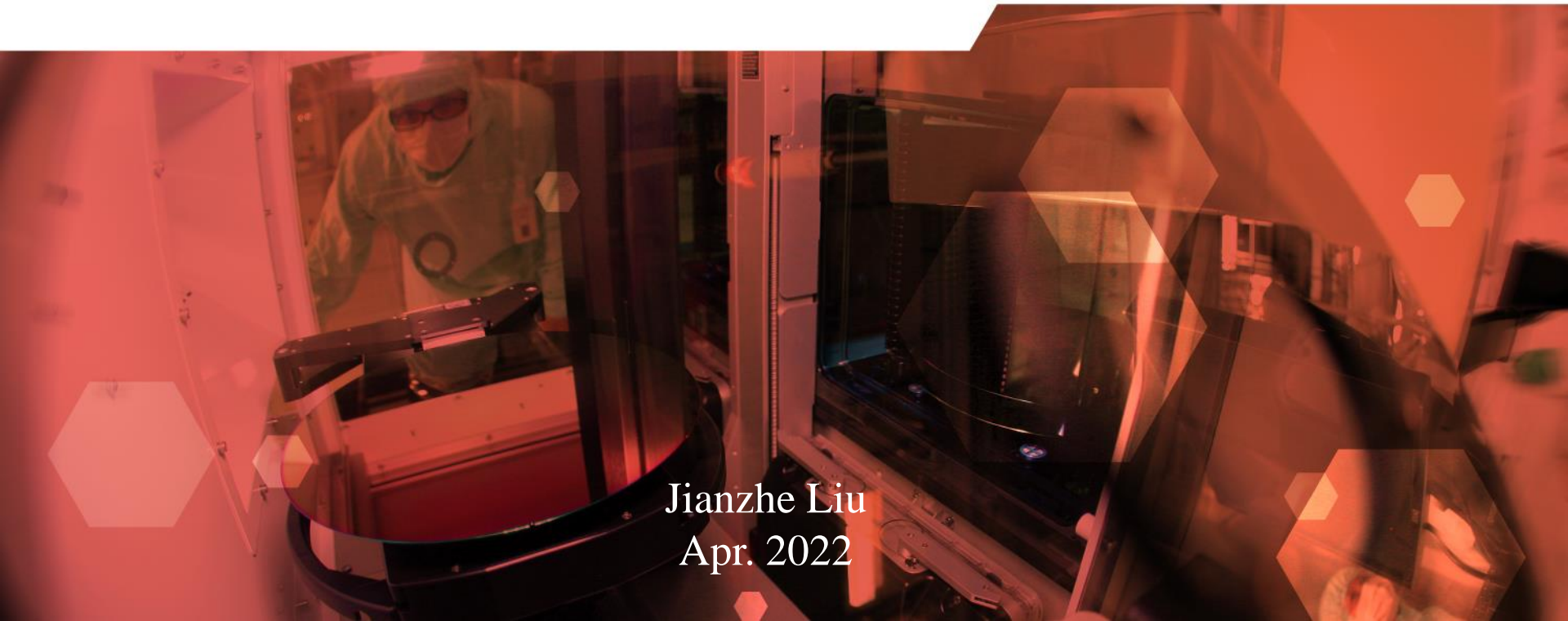


# Test Method for determining geometrical parameters of patterns on Patterned Sapphire Substrate



Jianzhe Liu  
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# 标准概况

## 一、标准名称

名称: 图形化蓝宝石衬底上图形的几何参数测试方法

**Title: Test Method for determining geometrical parameters of patterns on Patterned Sapphire Substrate**

## 二、立项

时 间: 2018年7月13日

**Time: July 13th, 2018**

文档编号: 6371C

**The document number : 6371C**

### 三、参与成员简介

牵头单位：博蓝特半导体

**Lead Unit: BST**

工作组成员：晶安光电、华灿光电、昂坤视觉、兆驰光电、哈工大、Mono。

**Team Members: Jing'an、HC semitek 、AK Optics、SZMTC、HIT、Monocrystal.**

# 全球投票意见及答复



## Cast Ballot Tally Summary

00 6371C - Std-HB-LED

6371C - Std-HB-LED New Standard: Test Method for Determining Geometrical Parameters of Patterns on Patterned Sapphire Substrate

**AcceptComments** AFF\_ITSDI 290498 - Vargas-Bernal, Rafael

Figure 13a was omitted.

**AbstainComments** Aff\_NAURA 498707 - Cao, Clark

change 'Instrument calibration for magnification and measurement performance shall be performed in accordance with ISO9001:2008 and or the instrument manufacturer's recommendations' to 'The analytical laboratory that performs the trace-metal contaminants should have a measurement quality-management system in accordance with ISO/IEC 17025:2017 or equivalent.'

**Total Voting Interests/Votes: 72/91**

**Voting Interest Accepts: 52 (100.00%)**

**No Rejects**

**Voting Interest Returns: 40**

**Return Percentage: 60.61%**

**Voting Interest Distribution: 66**

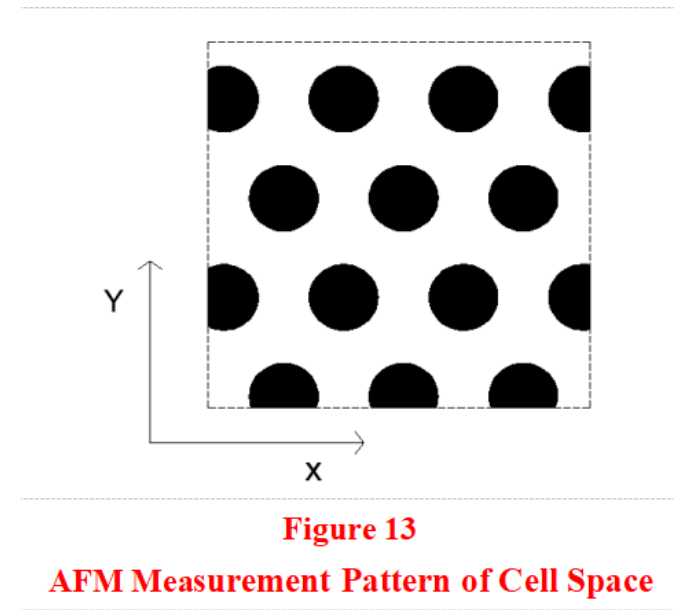
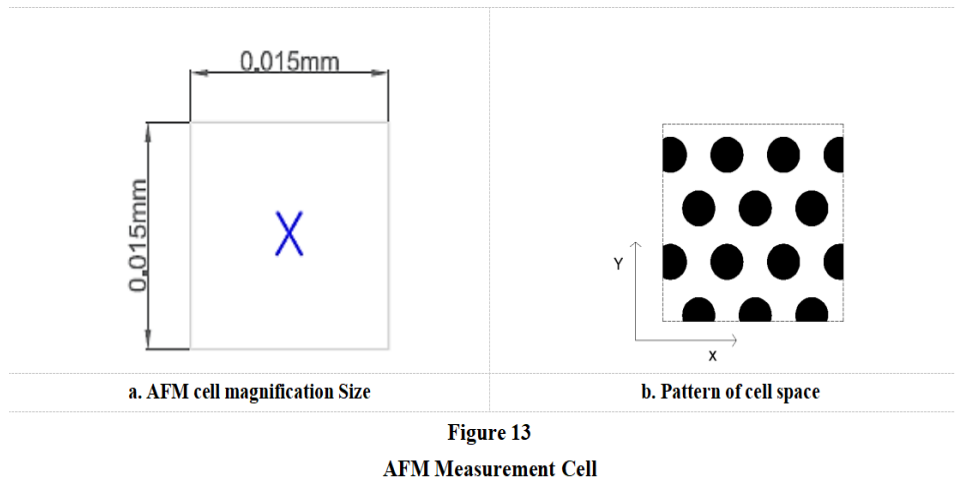
**290498 : Vargas-Bernal Rafael**

# Accept Comment : Vargas-Bernal, Rafael

- Accept Comment:

Figure 13a was omitted.

- Response : Agree



**498707: Cao, Clark**



# AbstainComments : Cao, Clark

- AbstainComments :
  - Change 'Instrument calibration for magnification and measurement performance shall be performed in accordance with ISO9001:2008 and or the instrument manufacturer's recommendations' to 'The analytical laboratory that performs the trace-metal contaminants should have a measurement quality-management system in accordance with ISO/IEC 17025:2017 or equivalent.'
- 

- Response : Agree

10.1.1 Instrument calibration for magnification and measurement performance shall be performed in accordance with ISO9001:2015, **ISO/IEC 17025:2017** and or the instrument manufacturer's recommendations.

**AMEC , Yingbin Liu**

# Comments : AMEC , Yingbin Liu

- Comments :
- 在6.7.3中，建议去掉“wide and narrow”。建议去掉“The required measurement data are used as shown in Table 3”，但保留后面color indicators may vary depending on equipment.

- 
- Response : Agree

6.7.3 Figure 10 is an example that shows the full picture of the reflectivity measuring the wafer. It can measure to read the gray scale by scanning whole surface of a wafer and the reflectivity changes according to the ~~wide and narrow~~ PSS diameter size and can be expressed in color on the wafer map. It can change colors depending on the setting. It shows that the shorter wavelength (Blue) is lower reflectivity and the longer wavelength (Red) is higher reflectivity. The ~~required measurement data are used as shown in Table 3, and~~ color indicators may vary depending on equipment.

# Comments : AMEC , Yingbin Liu

- Comments :
- 在10.2 反射率测量中提到了两种标准样品, measurement standard sample 以及 calibration standard sample, 它们是同一种东西还是两个 ?

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- Response : Agree

## 10.2 Wafer Mapping Measurements (Reflectivity)

10.2.1 Instrument calibration for measurement performance should be performed in accordance with the instrument manufacturer's recommendations.

10.2.2 Measurement standard sample is based on the Si wafer provided by the equipment manufacturer.

10.2.3 Reflectivity measurement value should be performed in accordance with the manufacturer's recommendations.

10.2.4 Measurement standard sample management should be replaced if abnormalities or damage or contamination occur.

10.2.5 Calibration Measurement standard samples shall be stored at designated locations.

# Comments : AMEC , Yingbin Liu

- Comments :
- 在6.5.1中checking beginning area of pattern within specification 中意思是edge area吗？

- 
- Response : Agree

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6.5 Test method for the effective area in the wafer

6.5.1 The effective area in the wafer can be specified by checking **beginning edge** area of pattern within specification.

## 申请发布

**I move that this Document passed TC Chapter review with technical changes and will be forwarded to the ISC A&R SC for procedural review. A Ratification Ballot will be issued to verify the technical changes.**

Thank you!